

Amendments to the Claims

Please amend claims 43, 47, 50, and 52 - 57, as indicated herein. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. - 42. (Cancelled)

43. (Currently amended) An actuation assembly comprising:

a gimbal;

a slider;

a slider bond pad for electrically connecting the slider to a trace layer ~~the gimbal~~, the slider bond pad having at least two layers;

a ball bond for connecting the slider bond pad to the trace layer ~~gimbal~~;

a notch located below the slider bond pad and on an edge of the slider, wherein the edge is adjacent the ~~gimbal~~; and

wherein the notch and the slider bond pad provide compensation for potential misalignment between the slider and the gimbal.

44. (Previously presented) The actuation assembly according to claim 43, wherein the notch has a height with respect to the gimbal of about 25 microns.

45. (Previously presented) The actuation assembly according to claim 43, wherein the slider bond pad has a thickness of about 15 microns.

46. (Previously presented) The actuation assembly according to claim 43, wherein the slider bond pad has a thickness of about 5 microns.

47. (Currently amended) An actuation assembly comprising:

~~a gimbal that includes~~ a flex on suspension bond pad electrically connected to a trace;

a slider body, wherein the slider body comprises a front side;
a slider bond pad extending from the front side for electrically connecting to the flex on suspension bond pad, the slider bond pad having a pad extension adjacent to the front side and a pad adjacent the pad extension;
a ball bond for electrically connecting the pad to the flex on suspension bond pad;
a notch located along the front side; and
wherein the notch and the slider bond pad provide compensation for potential misalignment between the slider and the flex on suspension bond pad.

48. (Previously presented) The actuation assembly according to claim 47, wherein the pad extension comprises nickel iron.

49. (Previously presented) The actuation assembly according to claim 48, wherein the pad comprises gold.

50. (Currently amended) The actuation assembly according to claim 47, wherein the slider bond pad has a thickness of about 5 microns. ~~49, further comprising a load beam connected to the gimbal~~

51. (Previously presented) The slider according to claim 49, wherein the slider bond pad has a thickness of about 15 microns.

52. (Currently amended) An actuation assembly comprising:

a slider;
a gimbal;
a bond pad for electrically connecting the slider to a trace ~~the gimbal~~, the bond pad having at least two layers;
a ball bond for connecting the bond pad to the trace ~~gimbal~~;

an indentation along an edge of the slider, wherein the indentation is proximate the bond pad and is positioned between the bond pad and the gimbal; and

wherein the indentation and the bond pad provide compensation for potential misalignment between the bond pad and the gimbal holding member.

53. (Currently amended) The actuation assembly device according to claim 52, wherein the at least two layers comprises a first layer and a second layer;

the first layer is proximate the slider and the second layer is proximate the first layer; and the first layer comprises nickel iron.

54. (Currently amended) The actuation assembly device according to claim 53, wherein the second layer comprises gold.

55. (Currently amended) The actuation assembly device according to 52, wherein the indentation has a height with respect to the gimbal of about 25 microns.

56. (Currently amended) The actuation assembly device according to claim 52, wherein the bond pad has a thickness of about 5 microns.

57. (Currently amended) The actuation assembly device according to claim 52, wherein the bond pad has a thickness of about 15 microns.